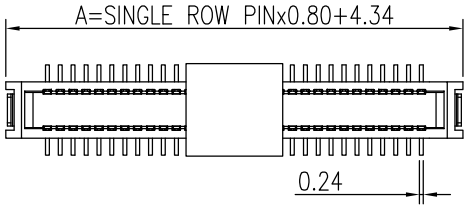
客户图

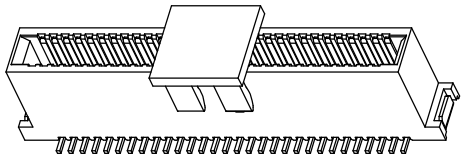
NOTES:

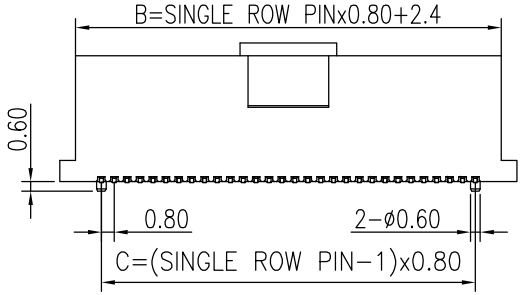
1. FINISH:
   - 1.1 HOUSING: LCP BLACK, UL94V-0.
   - 1.2 CONTACT: COPPER ALLOY,GOLD (SEE P/N) PLATED IN CONTACT AERA, GOLD FLASH PLATED IN SOLDER AREA, 50u" MIN. NICKEL UNDERPLATED OVERALL.
   - 1.3 GROUND: BRASS,80u" MIN. MATTE TIN PLATED OVER 50u" MIN. NICKEL UNDERPLATED OVERALL.
2. ELECTRICAL:
   - 2.1 CURRENT RATING: 0.5A.
   - 2.2 VOLTAGE RATING: 50V.
   - 2.3 CONTACT RESISTANCE: 120mΩ MAX.
   - 2.4 INSULATION RESISTANCE: 500MΩ MIN.
   - 2.5 OPERATION TEMPERATURE: -40°C TO +125°C.
3. ORDER INFORMATION:

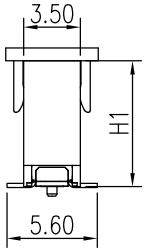
AA C8 M XXX XX 0XX R 1

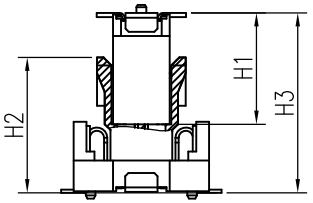
- Pin数码: 010:2x05PIN 120:2x60PIN
- 端子电镀: G0=Gold Flash, G1=1u" Gold, G2=3u" Gold, G3=5u" Gold, G4=10u" Gold, G5=15u" Gold, G6=30u" Gold
- 塑胶高度: 048=4.80mm("H1"), 068=6.80mm("H1"), 078=7.80mm("H1")
- 包装方式: R=TAPE REEL







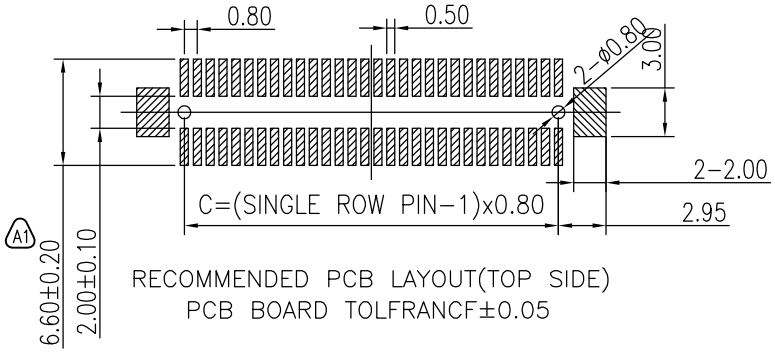




MATING HEIGHT

TABLE1:

No.OF PIN	Dimensions		
	A	B	C
010=2*05PIN	8.34	6.40	3.20
020=2*10PIN	12.34	10.40	7.20
030=2*15PIN	16.34	14.40	11.20
040=2*20PIN	20.34	18.40	15.20
050=2*25PIN	24.30	22.40	19.20
060=2*30PIN	28.34	26.40	23.20
080=2*40PIN	36.34	34.40	31.20
100=2*50PIN	44.34	42.40	39.20
120=2*60PIN	52.34	50.40	47.20



RECOMMENDED PCB LAYOUT(TOP SIDE)
PCB BOARD TOLFRANCF±0.05

MATING HEIGHT	H1	H2	H3
6.50mm	4.80	4.90	6.50
8.00mm	6.80		8.00
9.00mm	7.80		9.00
9.75mm	4.80	8.30	9.75
11.75mm	6.80		11.75
12.75mm	7.80		12.75

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE
A2	2022.05.07	更新PCB LAYOUT	WLY	
A1	2021.06.21	PIN针焊盘宽度由5.95修改为6.35	WLY	
A0		NEW	———	———

OPERATION		DRAW	WLY	2022.05.07
X.X	±0.40	DESIGN	Jensen	2022.05.07
X.XX	±0.25	CHECK	Jack	2022.05.07
X.XXX	±0.15	APPROVE	Andy	2022.05.07
Angle	±3°			
DIM.	TOL	UNIT	mm	SCALE 1:1

CONSHARE

SIZE	A4	PART NO.	AAC 8MXXXXX0XXR1
SHEET	1/1	TITLE:	浮动BTB PH0.80mm 公头直立式SMT TYPE
PROJ.		DRAW NO.	319